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## ABSTRACT OF THE DISCLOSURE

In a laser beam machining method for a wiring board, a machined portion of the wiring board is irradiated with a pulsed laser beam for a beam irradiation time ranging from about 10 to about 200  $\mu$ s and with energy density of about 20  $J/cm^2$  or more, thereby machining the wiring board, for example, drilling for a through-hole and a blind via hole, grooving, and cutting for an outside shape.